

6A, 700V, N-Channel MOSFET

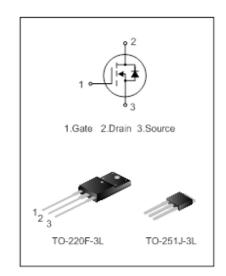
General Description

The GGVF6N70F/MJ is an N-channel enhancement mode power MOS field effect transistor. The improved planar stripe cell and the improved guard ring terminal have been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulses in the avalanche and commutation mode.

Features

- 6A, 700V
- $R_{DS(on(typ)}=1.35\Omega@V_{GS}=10V$
- Low gate charge
- Low Crss
- Fast switching
- Improved dv/dt capability

Nomenclature



Applications

- AC-DC power supplies
- DC-DC converters
- H-bridge PWM motor drivers

GG F X N E X X X G Halogen free Silan VDMOS Code Package information. of F-Cell process Example:F:TO-220F; Nominal current, using 1 or 2 digits: MJ:TO-251J. Example:4 denotes 4A, Nominal Voltage, using 2 digits 10 denotes 10A. Example: 70 denotes 700V 08 denotes 0.8A Special Features indication, May be omitted. N denotes N Channel Example: E denotes embeded ESD structure

Ordering Information

Part No.	Package Type	Marking	Material	Packing
GGVF6N70F	TO-220F-3L	GGVF6N70F	Pb free	Tube
GGVF6N70MJ	TO-251J-3L	GGVF6N70MJ	Pb free	Tube
GGVF6N70MJG	TO-251J-3L	GGVF6N70MJG	Halogen free	Tube

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GGVF6N70F/MJ(G)

6A, 700V, N-Channel MOSFET

Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Characteristics		-	Rat		
		Symbol	GGVF6N70F	GGVF6N70MJ(G)	Unit
Drain-Source Voltage		V _{DS}	7	V	
Gate-Source Voltage		V _{GS}	±	V	
Drain Current	T _C =25°C		6	A	
	T _C =100°C	Ι _D	3.		
Drain Current Pulsed		I _{DM}	24	А	
Power Dissipation(T _C =25°C)			45	128	W
-Derate above 25°C		PD	0.36	1.02	W/°C
Single Pulsed Avalanche Energy (Note 1)		E _{AS}	463		mJ
Operation Junction Temperature Range		TJ	-55~+150		°C
Storage Temperature Range		T _{stg}	-55~	°C	

Thermal Characteristics

	Symbol	Rati		
Characteristics		GGVF6N70F	GGVF6N70MJ(G)	Unit
Thermal Resistance, Junction-to-Case	R _{eJC}	2.78	0.98	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{ extsf{ heta}JA}$	120	110	°C/W

Electrical Characteristics (Tc=25°C, Unless Otherwise Specified)

Characteristics	Symbol	Test conditions	Min.	Тур.	Max.	Unit
Drain -Source Breakdown Voltage	B _{VDSS}	V _{GS} =0V, I _D =250µA	700			V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =700V, V _{GS} =0V			1.0	μA
Gate-Source Leakage Current	I _{GSS}	$V_{GS}=\pm 30V, V_{DS}=0V$			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{GS} = V _{DS} , I _D =250µA	2.0		4.0	V
Static Drain- Source On State Resistance	R _{DS(on)}	V _{GS} =10V, I _D =3.0A		1.35	1.7	Ω
Input Capacitance	Ciss			898.6		pF
Output Capacitance	Coss	V _{DS} =25V,V _{GS} =0V, f=1.0MHZ		94.7		
Reverse Transfer Capacitance	Crss			2.93		
Turn-on Delay Time	t _{d(on)}			24.73		ns
Turn-on Rise Time	tr	$V_{DD}=350V, I_{D}=6.0A, R_{G}=25\Omega$		37.87		
Turn-off Delay Time	t _{d(off)}	() - (- 0 0)		49.33		
Turn-off Fall Time	t _f	(Note 2,3)		29.67		
Total Gate Charge	Qg			16.53		
Gate-Source Charge	Q_gs	$V_{DS}=560V, I_{D}=6.0A, V_{GS}=10V$		4.82		nC
Gate-Drain Charge	Q_gd	(Note 2,3)		5.70		



Source-Drain Diode Ratings and Characteristics

Characteristics	Symbol	Test conditions	Min.	Тур.	Max.	Unit
Continuous Source Current	Is	Integral Reverse P-N			6.0	
Pulsed Source Current	I _{SM}	Junction Diode in the MOSFET			24.0	A
Diode Forward Voltage	V _{SD}	I _S =6.0A,V _{GS} =0V		-	1.4	V
Reverse Recovery Time	T _{rr}	I _S =6.0A,V _{GS} =0V,		531.25		ns
Reverse Recovery Charge	Q _{rr}	dl _F /dt=100A/µs(Note 2)		3.3		μC

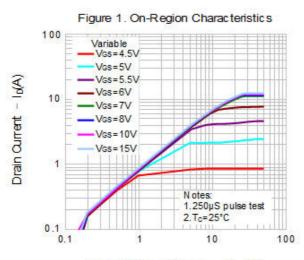
Notes:

- 1. L=30mH, I_{AS}=5.00A,V_{DD}=140V, R_G=25 Ω , starting T_J=25 $^{\circ}$ C;
- 2. Pulse Test: Pulse width \leq 300µs,Duty cycle \leq 2%;
- 3. Essentially independent of operating temperature.



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Typical Characteristics



Drain-Source Voltage - VDS(V)

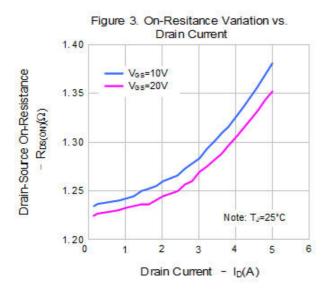


Figure 5. Capacitance Characteristics 2000 Ciss=Cgs+Cgd(Cds=shorted) Coss=Cds+Cgd 1800 Crss=Cgd 1600 1400 Capasistance(pF) 1200 1000 Ciss 800 Coss N otes 600 Crss 1. Vgs=0V 400 2. f=1MHz 200 0 0.1 1 10 100 Drain-Source Voltage - VDS(V)

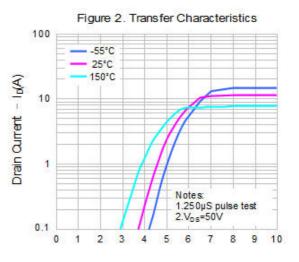




Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

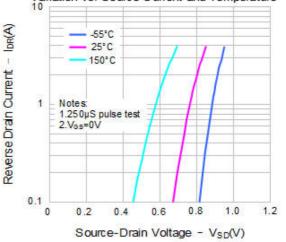
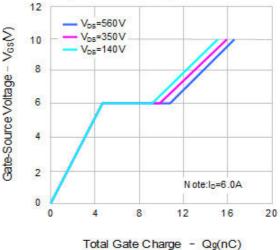


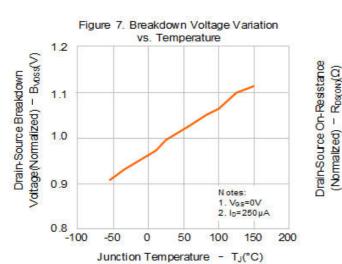
Figure 6. Gate Charge Characteristics

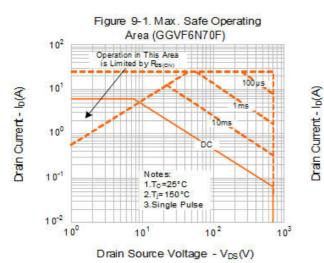


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Typical Characteristics (cont.)





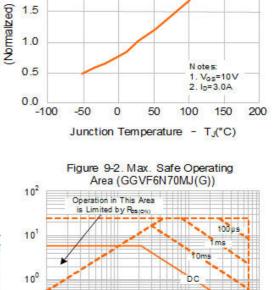


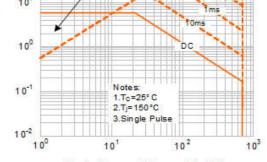
Figure 8. On-resistance Variation

vs. Temperature

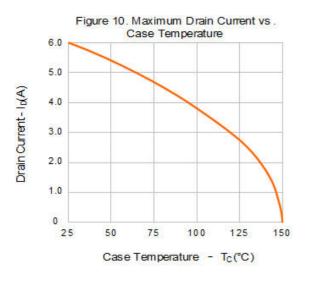
3.0

2.5

ຜ[ິ] 2.0



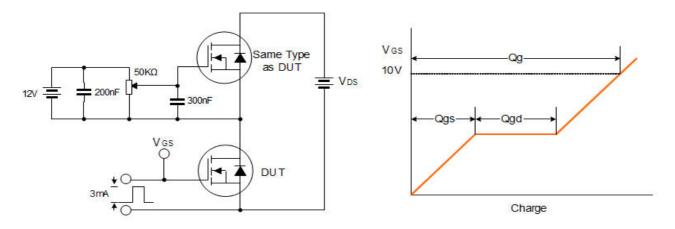
Drain Source Voltage - VDS(V)



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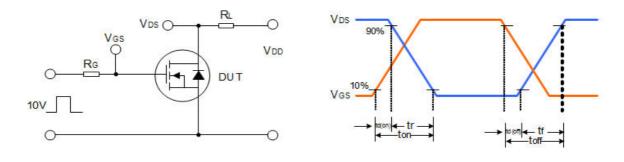


Typical Test Circuits

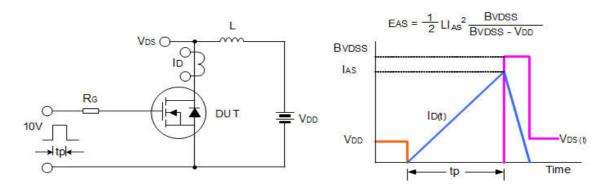


Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveform

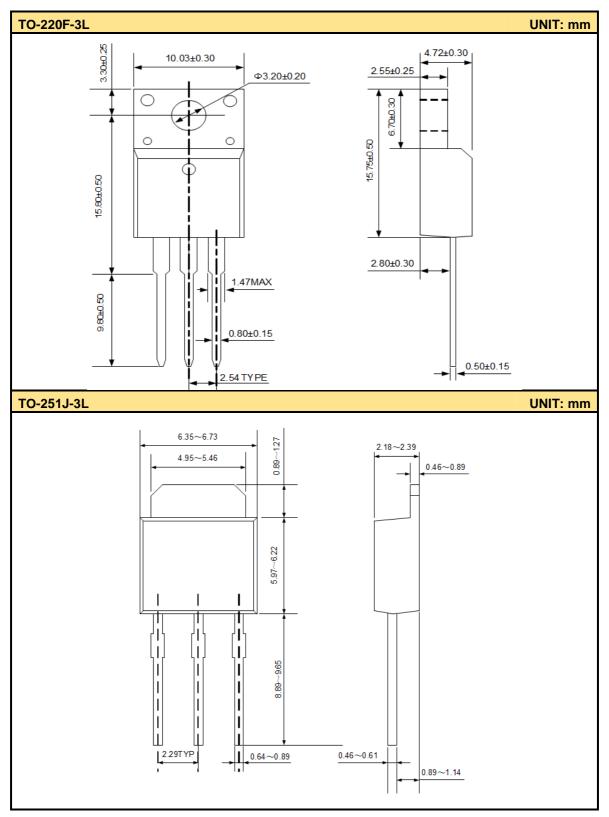


Unclamped Inductive Switching Test Circuit & Waveform





Package Outline





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